

Title (en)

METHOD FOR ATTACHING ELECTRONIC COMPONENTS TO A SUPPORT BY MEANS OF PRESSURE SINTERING AND CIRCUIT ARRANGEMENT

Title (de)

VERFAHREN ZUR BEFESTIGUNG VON ELEKTRONISCHEN BAUELEMENTEN AUF EINEM TRÄGER DURCH DRUCKSINTERUNG UND SCHALTUNGSANORDNUNG

Title (fr)

PROCÉDÉ DE FIXATION DE COMPOSANTS ÉLECTRONIQUES SUR UN SUPPORT PAR FRITTAGE SOUS PRESSION ET CIRCUITERIE

Publication

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Application

EP 07785597 A 20070706

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Abstract (en)

[origin: WO2008003308A1] The invention relates to a method for attaching electronic components (3) to a support by means of pressure sintering comprising the steps: a) coating at least one film (1) as support with a noble metal alloy (2); b) application of a metal containing contact layer (4) to contact surfaces of the at least one electronic component (3) for attaching; c) positioning the at least one electronic component (3) on the at least one film (1) such that the at least one contact surface rests on the noble metal alloy (2) of the at least one film (1) and d) subjecting the arrangement of at least one film (1) and at least one electronic component (3) to pressure and heat for pressure sintering.

IPC 8 full level

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CPC (source: EP)

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